



Evyap Sabun Malaysia Sdn Bhd

# Evyap Oleo O-1875 P

Oleic Acid Plus 75%

## Product Data Sheet

CAS No. 67701-08-0

EINECS No. 266-932-7

Parameter	Unit	Specification
Appearance at 30 Deg. C	-	Pale yellow liquid, free of foreign matter
Colour, Lovibond, Max	In 5,1/4" Cell	Y=8.0; R=1.0
Acid Value	mg KOH/Gm	195-205
Sap. Value	mg KOH/Gm	196-206
Iodine Value	Gms I2 / 100 Gms	90.0 – 105.0
Cloud point	° C	8.0 Max

Fatty Acid Composition	Unit	Specification
Up to C 18 (Saturated)	% by GC	12.0 Max
C 18:1	% by GC	75.0 Min
C 18:2	% by GC	18.0 Max
Others	% by GC	1.0 Max

The above chart indicates typical available specifications. Customised specifications are also available.

### APPLICATIONS

Food ingredients, esters, surfactants, transparent soaps, cosmetics and personal care products. Lubricants, metallic soaps, coatings and adhesives.

### PACKING

Available in standard 180kg MS/HDPE drums, IBC containers or flexi bags, Bulk ISO container loads. Customised packing size can be made available upon request.

### BEST BEFORE

24 months from the date of manufacturing in original containers, stored under standard conditions.

### CERTIFICATIONS

This product is Kosher certified by OK Kosher Certification (USA) & Halal certified by JAKIM (MALAYSIA). This product is manufactured in facility certified as per ISO 9001:2015, FSSC 22000, GMP+B2 by Lloyd's Register Quality Assurance and RSPO Supply Chain MB Certification Standard certified by SIRIM (MALAYSIA), Certificate Number: RSPO-SC 00157.

### **Evyap Sabun Malaysia Sdn Bhd**

**PLO 70, Jalan Nibong 4, Tanjung Langsat Industrial Complex, 81700 Pasir Gudang, Johor Darul Takzim, Malaysia.**

**Telephone: +607 252 7000; Fax: +607 252 0777,**

**Website: [www.evyapoleo.com](http://www.evyapoleo.com)**

**E-mail: [ESMSales@evyap.com.tr](mailto:ESMSales@evyap.com.tr)**

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